

| Chemical Name                   | Common Name                     | Type              | Equipment                   | Note         |
|---------------------------------|---------------------------------|-------------------|-----------------------------|--------------|
| A-174 Silane                    | Parylene Curing Agent           | Adhesion Agent    | Parylene Coater             |              |
| Acetic Acid                     | Acetic Acid                     | Acid              | -                           | PPE Required |
| Acetone                         | Acetone                         | Solvent           | -                           |              |
| Alumel                          | Alumel                          | Deposition Source | EBE                         |              |
| Aluminum                        | Al                              | Deposition Source | EBE, DC Sputter             |              |
| Aluminum / Silicon / Copper     | Al / Si / Cu                    | Deposition Source | Clustex                     |              |
| Aluminum / Copper               | Al / Cu                         | Deposition Source | Clustex                     |              |
| Aluminum Etchant                | Aluminum Etchant                | Etchant           | Light PPE                   |              |
| Aluminum Nitride                | Aluminum Nitride                | Deposition Source | RF Sputter                  |              |
| Aluminum Oxide                  | Aluminum Oxide, Al2O3           | Deposition Source | RF Sputter                  |              |
| AR 600-546                      | AR 600-547                      | EBL Developer     | -                           |              |
| AR 600-71                       | AR 600-72                       | EBL Stripper      | -                           |              |
| AR-P 6200.09                    | EBL Resist                      | EBL Resist        | -                           |              |
| AZ 300 MIF                      | AZ 300 MIF                      | Developer         | -                           |              |
| AZ 400T Stripper                | AZ 400T Stripper                | Stripper          | -                           |              |
| AZ 5214 EIR                     | AZ 5214 EIR                     | Developer         | -                           |              |
| AZ 726 MIF                      | AZ 726 MIF                      | Developer         | -                           |              |
| AZ Developer 1:1                | AZ Developer 1:2                | Developer         | -                           |              |
| Buffered Oxide Etch 7:1 Mixture | BOE                             | Acid              | -                           |              |
| Cerium Oxide                    | CeO2                            | Depost            | EBE                         | PPE Required |
| Chlorobenzene                   | Chlorobenzene                   | Solvent           | -                           |              |
| Chromium                        | Cr, Chrome                      | Deposition Source | EBE, DC Sputter             |              |
| Chromium Etchant                | Chromium Etchant                | Etchant           | -                           | PPE Required |
| Chromium Oxide                  |                                 | Deposition Source | Clustex                     |              |
| Cobalt                          | Co                              | Deposition Source | DC Sputter                  |              |
| Copper                          | Cu                              | Deposition Source | EBE, DC Sputter             |              |
| Copper Etchant                  | Copper Etchant                  | Etchant           | -                           | PPE Required |
| Copper Hydroxide                | Cu(OH)2                         | Powder            | MTI Annealing               |              |
| Copper Oxide                    |                                 | Deposition Source | Clustex                     |              |
| DPX-C                           | Parylene Dimer                  | Coating Agent     | Parylene Coater             |              |
| Erbium                          | Er                              | Deposition Source | EBE, DC Sputter             |              |
| Gallium Nitride                 | GaN                             | Deposition Source | EBE, RF Sputter             |              |
| Germaium                        | Ge                              | Deposition Source | EBE, RF Sputter             |              |
| Gold                            | Ag                              | Deposition Source | EBE                         |              |
| Gold Etchant                    | Gold Etchant                    | Etchant           | -                           | PPE Required |
| Graphite                        | C, Carbon                       | Substrate         | PECVD, RIE                  |              |
| Hafnium Nitride                 |                                 | Deposition Source | Clustex                     |              |
| Hydrochloric Acid               | HCl                             | Acid              | -                           | PPE Required |
| Hydrofluoric Acid 49%           | HF                              | Acid              | -                           | PPE Required |
| Hydrogen Peroxide 30%           | Peroxide                        | Peroxide          | -                           |              |
| Indium                          | In                              | Deposition Source | EBE                         |              |
| Indium Antimonide               | InSb                            | Deposition Source | RF Sputter                  |              |
| Indium Oxide / Tin Oxide        |                                 | Deposition Source | Clustex                     |              |
| Indium Tin Oxide                | ITO                             | Deposition Source | RF Sputter                  |              |
| Iron                            | Fe                              | Deposition Source | EBE, DC Sputter             |              |
| Iron(III) Oxide Etchant         | Iron(III) Oxide Etchant         | Etchant           | -                           |              |
| Isopropyl Alcohol               | IPA                             | Solvent           | -                           |              |
| Lithium Hydroxide               | Li(OH)                          | Base              | Use in wet bench in Bay 1   |              |
| Lithium Niobate                 | LiNbO3                          | Substrate         | EBE, DC Sputter             |              |
| Lithium Tantalum Oxide          | LiTaO3                          | Deposition Source | RF Sputter                  |              |
| Machinable Glass Ceramic        | MACOR, Ceramic                  | Substrate         | EBE, DC Sputter, RF Sputter |              |
| Magnesium                       | Mg                              | Deposition Source | EBE                         |              |
| Methanol                        | Methanol                        | Solvent           | -                           |              |
| MIBK:IPA 1:3                    | EBL Developer                   | Developer         | -                           |              |
| Microposit MF-319               | Microposit MF-320               | Developer         | -                           |              |
| Microposit S1818                |                                 | Photoresist       |                             |              |
| Molybdenum                      |                                 | Deposition Source | EBE, DC Sputter, Clustex    |              |
| Molybdenum Trioxide             | MoO3                            | Deposition Source | RF Sputter, Clustex         |              |
| Nickel Etchant                  | Nickel Etchant, Ferric Chloride | Etchant           | -                           | PPE Required |
| Nickel                          | Ni                              | Deposition Source | EBE, DC Sputter             |              |
| Nickel Oxide                    | NiO                             | Deposition Source | Clustex                     |              |
| Niobium                         | Nb                              | Deposition Source | DC Sputter                  |              |
| Niobium Nitride                 | NbN                             | Deposition Source | Clustex                     |              |
| Niobium Oxide                   | NbO                             | Deposition Source | Clustex                     |              |
| Nitric Acid                     | Nitric Acid                     | Acid              | -                           | PPE Required |
| Palladium                       | Pd                              | Deposition Source | DC Sputter                  |              |
| Phosphoric Acid                 | Phosphoric Acid                 | Acid              | -                           | PPE Required |
| Platinum                        | Pt                              | Deposition Source | EBE, DC Sputter             |              |
| Poly (methyl methacrylate)      | PMMA                            | EBL Resist        | -                           |              |

|                                       |                                |                         |                                      |              |
|---------------------------------------|--------------------------------|-------------------------|--------------------------------------|--------------|
| Polyethylenimine                      | PEI                            | Substrate               | RF Sputter                           |              |
| Polyethylene Terephthalate            | PET                            | Substrate               | RF Sputter                           |              |
| Polystyrene                           | PS                             | Substrate               | RF Sputter                           |              |
| Potassium Hydroxide                   | KOH                            | Etchant                 | -                                    |              |
| Propylene Glycol Methyl Ether Acetate | PGMEA, NanoScribe              | Developer               | -                                    |              |
| Rhodium                               | Rh                             | Deposition Source       | DC Sputter                           |              |
| Ruthenium                             | Ru                             | Deposition Source       | DC Sputter                           |              |
| Ruthenium Oxide                       |                                | Deposition Source       | Clustex                              |              |
| S1818                                 | S1819                          | Photoresist             | -                                    |              |
| Silicon                               | Si                             | Deposition Source       | EBE, DC Sputter, RF Sputter, Clustex |              |
| Silicon Nitride                       | SiNx                           | Deposition Source       | Clustex                              |              |
| Silicon Oxide                         | SiO2                           | Deposition Source       | EBE, RF Sputter                      |              |
| Silver                                | Ag                             | Deposition Source       | Clustex, EBE, DC Sputter             |              |
| Strontium Titanium Oxide              | STO                            | Deposition Source       | Clustex                              |              |
| SU-8                                  | SU-8                           | Photoresist             | -                                    |              |
| Sulfuric Acid                         | Sulfuric Acid                  | Acid                    | -                                    | PPE Required |
| Sylgard 184 Silicone Elastomer        | Sylgard 184 Silicone Elastomer | Transparent Encapsulant | -                                    |              |
| Sylgard Curing Agent                  | Sylgard Curing Agent           | Transparent Encapsulant | -                                    |              |
| Tantalum                              | Ta                             | Deposition Source       | EBE, DC Sputter                      |              |
| Tantalum / Aluminum                   | Ta / Al                        | Deposition Source       | Clustex                              |              |
| Tantalum Carbide                      | TaC                            | Deposition Source       | Clustex                              |              |
| Tantalum Nitride                      | TaN                            | Deposition Source       | RF Sputter                           |              |
| Tantalum Oxide (Ta2O5)                | TaO5                           | Deposition Source       | Clustex                              |              |
| Tantalum Oxide (TaO1.8)               | Ta1.8                          | Deposition Source       | Clustex                              |              |
| Tantalum Oxide (TaO2)                 | TaO2                           | Deposition Source       | Clustex                              |              |
| Tantalum Oxide(TaO2.2)                | TaO2.2                         | Deposition Source       | Clustex                              |              |
| Tantalum Silicide                     | TiSi2                          | Deposition Source       | Clustex                              |              |
| Tetramethylammonium Hydroxide         | TMAH, TMAOH                    | Developer               | -                                    | PPE Required |
| Titanium                              | Ti                             | Deposition Source       | EBE, DC Sputter                      |              |
| Titanium Carbide                      | TiC                            | Deposition Source       | Clustex                              |              |
| Titanium Etchant                      | TFTN                           | Etchant                 | -                                    | PPE Required |
| Titanium Nitride                      | TiN, Ti-Nitride                | Deposition Source       | RF Sputter                           |              |
| Titanium Oxide                        | TiO, Ti-Oxide                  | Deposition Source       | EBE, Clustex                         |              |
| Trichloroethylene                     | TCE                            | Solvent                 | -                                    |              |
| Tris(hydroxymethyl)aminomethane       | THAM                           | Substrate               |                                      |              |
| Tungsten                              | W                              | Deposition Source       | DC Sputter                           |              |
| Tungsten Oxide                        |                                | Deposition Source       | Clustex                              |              |
| Turpentine Oil                        | Turpentine, Oil of Turpentine  | Solvent                 | -                                    |              |
| Vanadium Oxide                        | VO2                            | Deposition Source       | Clustex                              |              |
| Vermiculite Clay                      | VMT                            | Substrate               |                                      |              |
| Xylene                                | Xylene                         | Solvent                 | -                                    |              |
| Ytterbium                             | Yb                             | Deposition Source       | EBE                                  |              |
| ZDMAC                                 | ZDMAC                          | EBL Stripper            | -                                    |              |
| ZED-N50                               | ZED-N51                        | EBL Developer           | -                                    |              |
| ZEP520                                | ZEP521                         | EBL Resist              | -                                    |              |
| Zinc Oxide                            | ZnO                            | Deposition Source       | RF Sputter                           |              |
| Zirconium                             | Zr                             | Deposition Source       | DC Sputter                           |              |
| Zirconium Clustex                     |                                | Deposition Source       | Clustex                              |              |
| Zirconium Oxide                       |                                | Deposition Source       | Clustex                              |              |